### 800V N-Channel MOSFET

#### **FEATURES**

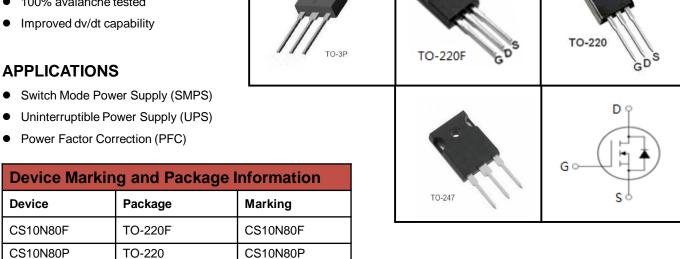
- Fast switching
- 100% avalanche tested

CS10N80V

CS10N80W

TO-3P

TO-247



CS10N80V

CS10N80W

Parameter		Symbol	Value				
			TO-220F	TO-220	TO-247	TO-3P	- Uni
Drain-Source Voltage (V <sub>GS</sub> = 0V)		V <sub>DSS</sub>	800				V
Continuous Drain Current		I <sub>D</sub>	10				А
Pulsed Drain Current	(note1)	I <sub>DM</sub>	40				А
Gate-Source Voltage		$V_{GSS}$	±30			V	
Single Pulse Avalanche Energy	(note2)	E <sub>AS</sub>	605				mJ
Avalanche Current	(note1)	I <sub>AS</sub>	11				Α
Repetitive Avalanche Energy	(note1)	E <sub>AR</sub>	363				mJ
Power Dissipation (T <sub>C</sub> = 25°C)		P <sub>D</sub>	25 70			W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55~+150			°C	

Thermal Resistance							
Borometer	0		l lm:4				
Parameter	Symbol TO-220F		TO-220	TO-247	TO-3P	Unit	
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	5		1.78		12/\\\	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5		60		K/W	



<b>-</b>	0	T	Value				
Parameter	Symbol	Test Conditions	Min.	Min. Typ. Max		Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	800			V	
Zoro Coto Voltago Drain Current	I <sub>DSS</sub>	$V_{DS} = 800V, V_{GS} = 0V, T_{J} = 25^{\circ}C$	-		1		
Zero Gate Voltage Drain Current		$V_{DS} = 640V, V_{GS} = 0V, T_{J} = 125^{\circ}C$	1		100	μA	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V	
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> =5A		0.8	1	Ω	
Dynamic							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0V$ ,		1907		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 25V$ ,		223			
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		56			
Total Gate Charge	$Q_g$			78		nC	
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 640 \text{V}, I_{D} = 10 \text{A}, $ $V_{GS} = 10 \text{V}$		10			
Gate-Drain Charge	$Q_{gd}$	. 55		34			
Turn-on Delay Time	t <sub>d(on)</sub>			49			
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 400V, I_{D} = 10A,$		24			
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		472		ns	
Turn-off Fall Time	t <sub>f</sub>			529			
Drain-Source Body Diode Character	istics						
Continuous Body Diode Current	I <sub>S</sub>	T 05.00			10		
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C	-		40	Α	
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}\text{C}, I_{SD} = 5\text{A}, V_{GS} = 0\text{V}$			1.4	V	
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 10A,$		1097		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt =100A /μs		6.6		μC	

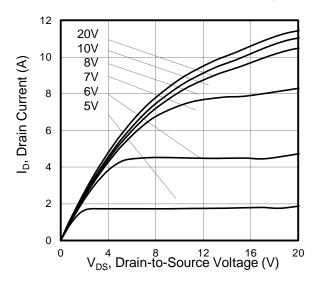
#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=10mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%



### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics (T<sub>J</sub> = 25°C)



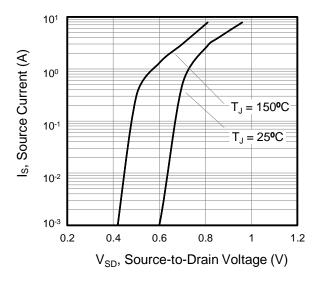


Figure 2. Body Diode Forward Voltage

Figure 3. Drain Current vs. Temperature

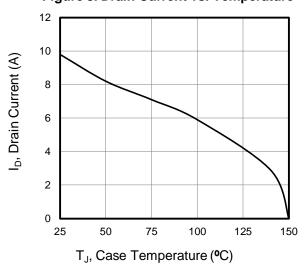


Figure 4. BV<sub>DSS</sub> Variation vs. Temperature

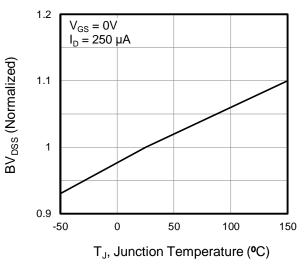


Figure 5. Transfer Characteristics

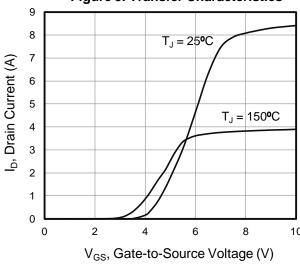
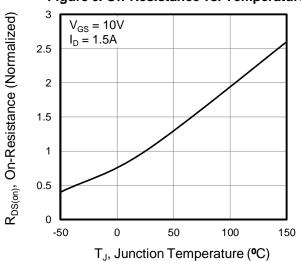


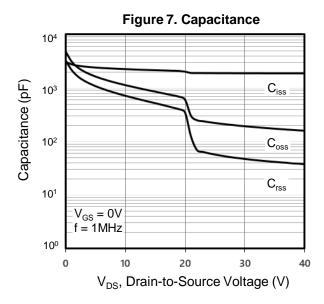
Figure 6. On-Resistance vs. Temperature





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### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



V<sub>DD</sub> = 160V V<sub>DD</sub> = 400V V<sub>DD</sub> = 640V V<sub>DD</sub> = 640V V<sub>DD</sub> = 640V Q<sub>D</sub> = 640V Q<sub>D</sub> = 640V Q<sub>D</sub> = 640V

Figure 8. Gate Charge

Figure 9. Transient Thermal Impedance

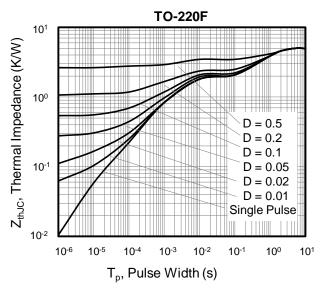


Figure 10. Transient Thermal Impedance

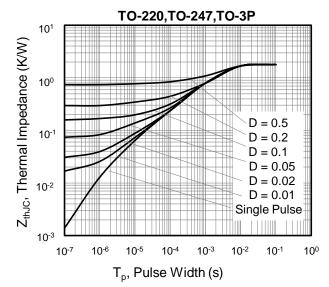




Figure A: Gate Charge Test Circuit and Waveform

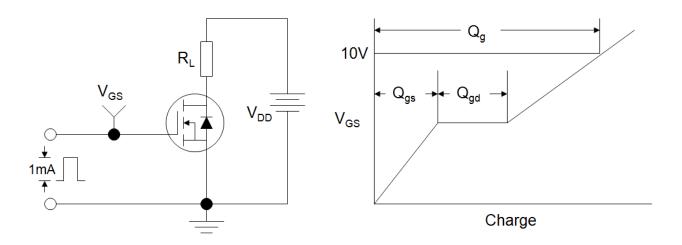


Figure B: Resistive Switching Test Circuit and Waveform

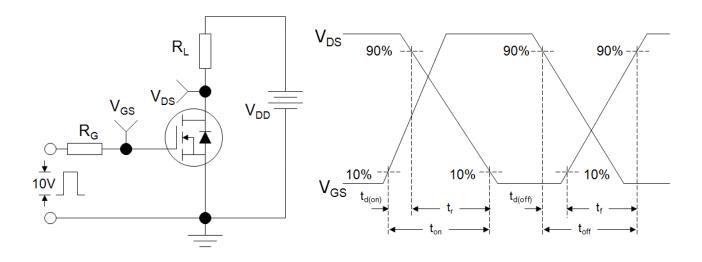
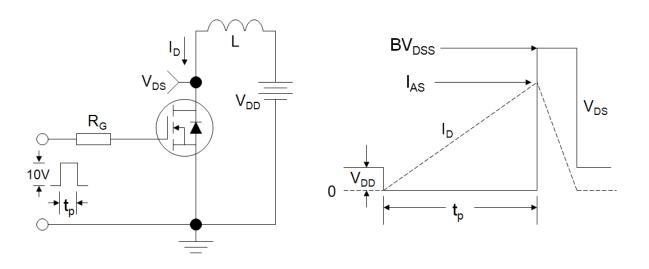
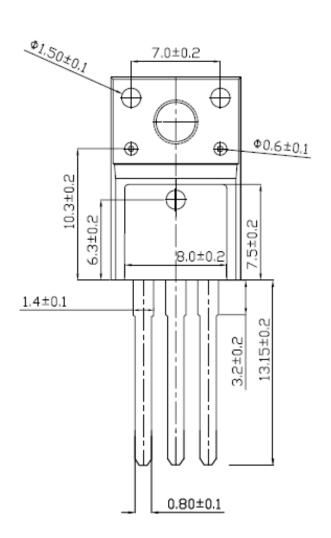


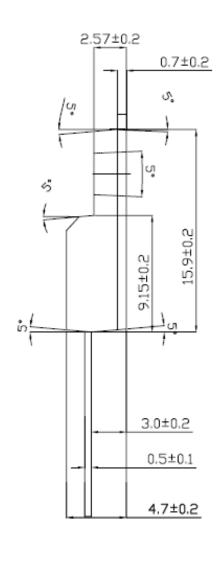
Figure C: Unclamped Inductive Switching Test Circuit and Waveform



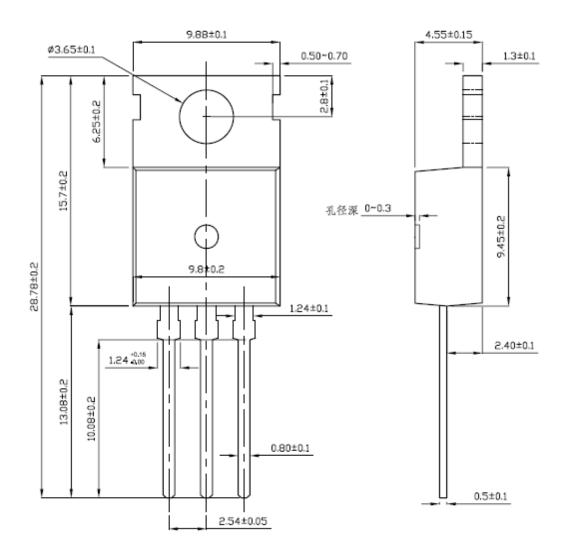


### **TO-220F**

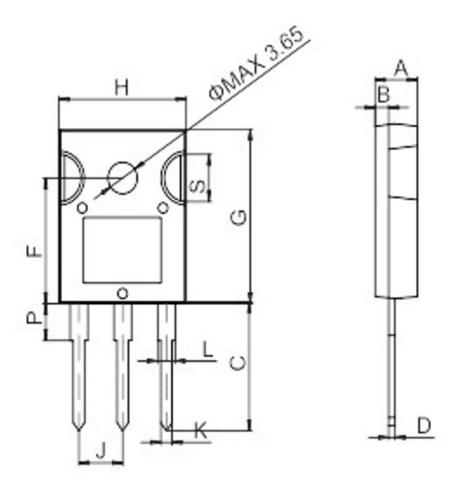




### **TO-220**

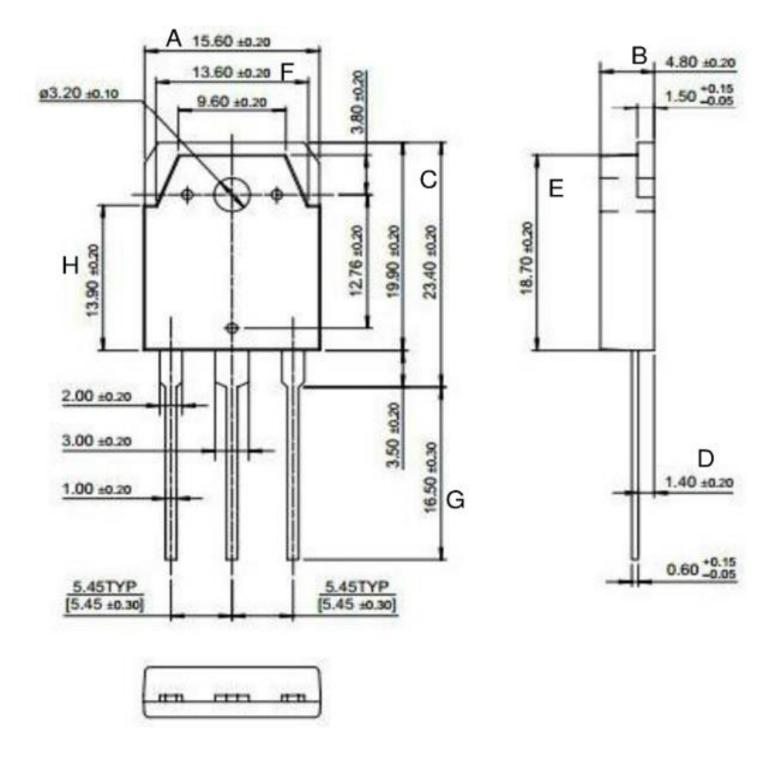


**TO-247** 



Ref.	Dimensions								
	1	MIIImete	rs	Inches					
	Min.	Тур.	Max.	Min.	Тур.	Max.			
Α	4.9		5.4	0.193		0.213			
В	1.6		2.0	0.063		0.079			
С	14.35		15.4	0,565		0,606			
D	0.5		0.8	0.020		0.031			
F	14.4		15.1	0.567		0.594			
G	19.7		20.6	0.775		0.81			
Н	15.4		16.2	0.606		0.638			
J	5.3		5.6	0.209		0.220			
K	1.3		1.5	0.051		0.059			
L	2.8		3.3	0.110		0.130			
Р	3.7		4.2	0.146		0.165			
S	5.35		5.65	0.211	\$ ±	0.222			

**TO-3P** 



V3.1



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